

**Product / Package Information**

<b>Package</b>	LFCSP - Punched
<b>Body Size (mm)</b>	9 X 9 X 0.85 (5.2 EP)
<b>Lead Count</b>	64
<b>Terminal Finish</b>	100 Sn

**Environmental Information**

<b>RoHS Compliant</b>	Yes
<b>High Temperature Compliant</b>	Yes
<b>Halogen Free Compliant</b>	Yes
<b>REACH SVHC Compliant</b>	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	9.05E-02	86.9	869100	33.74		337365
Thermosets	Epoxy & Phenol Resin	Proprietary	1.33E-02	12.8	127800	4.96		49609
Other inorganic materials	Carbon black	1333-86-4	3.23E-04	0.3	3100	0.12		1203
<b>Subtotal</b>			<b>1.04 E-01</b>	<b>100.00</b>	<b>1000000</b>	<b>38.82</b>		<b>388177</b>

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	1.43 E-01	97.5	975000	53.19		531923
Copper & its alloys	Iron	7439-89-6	3.44 E-03	2.35	23500	1.28		12821
Copper & its alloys	Zinc	7440-66-6	1.76 E-04	0.12	1200	0.07		655
Copper & its alloys	Phosphorus	7723-14-0	4.39 E-05	0.03	300	0.02		164
<b>Subtotal</b>			<b>1.46 E-01</b>	<b>100.00</b>	<b>1000000</b>	<b>54.56</b>		<b>545562</b>

**Internal Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	1.46 E-03	100.0	1000000	0.55		5456

**External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	2.96 E-03	100.0	1000000	1.11		11050

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	1.11 E-03	100.0	1000000	0.41		4122

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	1.07 E-02	100.0	1000000	3.99		39882

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	1.13 E-03	73.54	735400	0.42		4229
Other organic materials	Epoxy resin A	TS ref# 10013	1.13 E-04	7.35	73500	0.04		423
Others	Anhydride	TS ref# 10181	1.13 E-04	7.35	73500	0.04		423
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	4.54 E-05	2.94	29400	0.02		169
Other organic materials	Epoxy resin B	TS ref# 10237	4.54 E-05	2.94	29400	0.02		169
Others	Epoxy resin modifier	TS ref# 10038	4.54 E-05	2.94	29400	0.02		169
Others	Anhydride	TS ref# 10180	4.54 E-05	2.94	29400	0.02		169
<b>Subtotal</b>			<b>1.54 E-03</b>	<b>100.0</b>	<b>1000000</b>	<b>0.58</b>		<b>5751</b>

<b>Package Totals</b>			<b>Weight (g)</b> 2.68 E-01			<b>Percentage (%)</b> 100		<b>PPM</b> 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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